

61.(NEW) An electronic component mounting method as claimed in claim 28, wherein the gold bump that has an approximately conically shaped tip is formed on the electrode of the electronic component by means of the capillary that has a chamfer angle ( $\theta_c$ ) of not greater than  $100^\circ$  when a gold ball (96a) is formed by an electric spark at a tip of a gold wire (95) similarly to the wire bonding in forming the bump on the electronic component and a tip shape provided with no flat portion to be brought in contact with the gold ball.

62.(NEW) An electronic component unit, wherein the electronic component is mounted on the board by the electronic component mounting method claimed in claim 5.

63.(NEW) An electronic component unit, wherein the electronic component is mounted on the board by the electronic component mounting method claimed in claim 8.

64.(NEW) An electronic component unit, wherein the electronic component is mounted on the board by the electronic component mounting method claimed in claim 25.

65.(NEW) An electronic component unit, wherein the electronic component is mounted on the board by the electronic component mounting method claimed in claim 28.

66.(NEW) An electronic component mounting apparatus as claimed in claim 34, wherein the apparatus for metallically bonding the gold bump to the electrode of the board with supersonic waves applied comprises a heating member for effecting heating from the upper surface side of the electronic component or from the board side or from both the electronic component side and the board side, and the heating is effected by the heating member at a time of metallic bonding.

67.(NEW) An electronic component mounting method as claimed in claim 5, wherein the inorganic filler is constructed of ceramics of spherical or pulverized silica, alumina, or the like.

68.(NEW) An electronic component mounting method as claimed in claim 8, wherein the inorganic filler is constructed of ceramics of spherical or pulverized silica, alumina, or the like.

69.(NEW) An electronic component mounting method as claimed in claim 25, wherein the inorganic filler is constructed of ceramics of spherical or pulverized silica, alumina, or the like.

70.(NEW) An electronic component mounting method as claimed in claim 28, wherein the inorganic filler is constructed of ceramics of spherical or pulverized silica, alumina, or the like.

71.(NEW) An electronic component mounting method as claimed in claim 31, wherein the inorganic filler is constructed of ceramics of spherical or pulverized silica, alumina, or the like.